

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	0	("second built up structure" near5 "solder resist").clm.	US-PGPUB	OR	ON	2010/01/22 12:54
S1	2	"10509899"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 13:20
S2	11876	"package substrate"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 14:09
S3	3732	S2 and ("dielectric" "inter-layer dielectric" "insulat\$3" "isolation" )	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 14:10
S4	608	S3 and optical	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 14:18
S5	546	S4 and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 14:21
S6	169	S5 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 14:22
S7	85	("4183041"   "4710798"   "4751482"   "5090609"   "5381039").PN. OR ("5523622").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/10 14:38
S8	85065	hitachi	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/10 14:58
S9	5537	S8 and (package and substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 14:58
S10	2780	S9 and ("dielectric" "inter-layer dielectric" "insulat\$3" "isolation" )	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 14:59
S11	1306	S10 and optical	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 14:59
S12	1032	S11 and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:00
S13	344	S12 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:00

S14	3642	(257/621,774).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/06/10 15:22
S15	3209	S14 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:23
S16	1976	S15 and ("dielectric" "inter-layer dielectric" "insulat\$3" "isolation" )	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:23
S17	202	S16 and optical	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:23
S18	140	S17 and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:23
S19	68	S18 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:23
S20	8056	(257/686,777,E25.006, E25.013,E25.018,E25.021, E25.027,E23.085,E21.614). CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/06/10 15:35
S21	6224	S20 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:35
S22	2348	S21 and ("dielectric" "inter-layer dielectric" "insulat\$3" "isolation" )	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:36
S23	448	S22 and optical	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:36
S24	140	S18 and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:36
S25	68	S24 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:36
S26	2	"11513249"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:41
S27	1892	(257/698).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/06/10 15:54
S28	1385	S27 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:54
S29	572	S28 and ("dielectric" "inter-layer dielectric" "insulat\$3" "isolation" )	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:55
S30	74	S29 and optical	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:55

S31	70	S30 and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:55
S32	32	S31 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 15:55
S33	2	"20020159243"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:04
S34	2	"20020033378"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:05
S35	18486	"NGK spark"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:08
S36	18477	"NGK spark plug"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:08
S37	3480	S36 and (substrate pcb "printed circuit board" pwb "printed wiring board")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:09
S38	632	S37 and ("dielectric" "inter- layer dielectric" "insulat\$3" "isolation" )	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:10
S39	15	S38 and optical	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:10
S40	69	S38 and (optical optic light)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:11
S41	49	S40 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:11
S42	17	("0002002"   "0002003"   "0002004"   "20050185880"   "0000005"   "5105237"   "5623178"   "0555633"   "6343171"   "6661939"   "6788874").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/10 16:39
S43	2	"20070194357"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/11 07:28
S44	2	S43 and ("conductive film" aperture "incident light" photodiode "semiconductor layer")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/11 07:30
S45	57	"5200631"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/11 13:42

S46	2	("5952712").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/06/11 13:44
S47	2	("6836020").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/06/11 13:45
S48	3	("6603198").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/06/11 13:46
S49	2	("5994771").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/06/11 13:46
S50	11	("4640010"   "5041943"   "5306670"   "5521332"   "5828126").PN. OR ("5994771").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 13:47
S51	18	("4617730"   "5615477"   "5854534"   "5883335"   "5994771"   "6051867"   "6107109"   "6114019"   "6229209"   "6239495"). PN. OR ("6392301").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 13:48
S52	31	("20010008313"   "20010052829"   "20020003049"   "3612744"   "3634782"   "3700825"   "4524239"   "4560962"   "4644092"   "4855537"   "4859806"   "5300899"   "5334800"   "5360949"   "5410107"   "5479138"   "5519176"   "5562498"   "5637834"   "5675299"   "5682124"   "5942849"   "6045927"   "6081035"   "6184477"   "6225687"   "6236302"   "6255600"   "6303871"   "6392301"   "6559377"). PN. OR ("7243423").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 13:57
S53	8	("6045927").PN. OR ("6225687").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 13:58
S54	18	("4617730"   "5615477"   "5854534"   "5883335"   "5994771"   "6051867"   "6107109"   "6114019"   "6229209"   "6239495"). PN. OR ("6392301").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 14:03
S55	10	("6272020"   "6326561"   "6329610"   "6370013"   "6373000"   "6392301"   "6426470"   "6480395"   "6495770"   "6506982"). PN. OR ("7102085").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 14:03

S56	8	("5619476"   "5870351"   "5894452"   "6430109"   "6674126").PN. OR ("6836020").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 14:10
S57	57	("3968564"   "4452508"   "4734384"   "4744623"   "4920070"   "4970578"   "5039189"   "5128831"   "5200631"   "5221633"   "5312765"   "5352998"   "5362976"   "5409563"   "5416872"   "5431775"   "5483614"   "5489554"   "5532506"   "5587119"   "5604835"   "5618752"   "5641545"   "5652811"   "5656548"   "5682062"   "5729038"   "5739067"   "5742100"   "5760478"   "5767001"   "5796714"   "5798297"   "5834849"   "5844289"   "5848214"   "5858814"   "5858877"   "5897333"   "5900674"   "5901050"   "5902118"   "5903045"   "5915167"   "5952665"   "5963088"   "6087899"   "6090636"   "6122187"   "6143616"   "6150188"   "6181864"   "6187677"   "6198168"   "6281042"   "6777715"   "6995441").PN. OR ("7164156").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 14:16
S58	65	("3748548"   "4396437"   "4450464"   "4547792"   "4782023"   "4902637"   "4972248"   "4978639"   "5039628"   "5077231"   "5084742").PN. OR ("5312765").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 14:18
S59	65	("3429040"   "4070516"   "4169001"   "4573067"   "4626878"   "4699449"   "4729618"   "4758063"   "4871224"   "4966430"   "5049982").PN. OR ("5200631").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 14:26

S60	48	("4530152"   "4663652"   "4691225"   "4760440"   "4801998"   "4864470"   "5118370"   "5200631"   "5241133"   "5331512"   "5336931"   "5352852"   "5357056"   "5371404"   "5436203"   "5438216"   "5478007"   "5495450"   "5577319"   "5639989"   "5654243"   "5656857"   "5753857"   "5776798"   "5784260"   "5786589"   "5808330"   "5861680"   "5866953"   "5867368"   "5893723"   "5895222"   "5939784"   "5949655"   "5950074"   "5962810"   "5969461"   "5972738"   "5981314"   "5989941"   "6034429"   "6092281"   "6117705").PN. OR ("6448635").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 14:33
S61	16	("0002002"   "0002003"   "0002004"   "20050185880"   "0000005"   "5105237"   "5623178"   "0555633"   "6343171"   "6661939"   "6788874").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 15:21
S62	10	2001-185752	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 15:34
S63	0	"2001185752"	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 15:35
S64	10	"2001-185752"	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 15:35
S65	26	"5297234"	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 15:35
S66	1	"7248421"	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/11 15:36
S67	58671	("through wafer" "through substrate")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/12 07:18
S68	3449	S67 and "optical path"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/12 07:18
S69	30	S68 and ("optical path" near5 resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/12 07:19
S70	7	S69 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/06/12 07:19

S71	33	("3560257"   "4499655"   "4733291"   "4991090"   "5065228"   "5198695"   "5229647"   "5325265"   "5386142"   "5399898"   "5404044"   "5406125"   "5530288"   "5552633"   "5825080").PN. OR ("5952712").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/12 08:34
S72	64	("3968564"   "4920070"   "4970578"   "5128831"   "5221633"   "5352998"   "5362796"   "5409563"   "5489554"   "5532506"   "5604835"   "5641545"   "5656548"   "5682062"   "5729038"   "5742100"   "5744379"   "5760478"   "5767001"   "5798297"   "5834849"   "5844289"   "5858814"   "5897333"   "5900674"   "5901050"   "5902118"   "5903045"   "5915167"   "5952665"   "5952712").PN. OR ("6090636").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/12 08:38
S73	3056613	(substrate pcb "printed circuit board" pwb "printed wiring board")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:36
S74	322780	S73 and (substrate pcb "printed circuit board" pwb "printed wiring board" "mounting plate" "mounting substrate" "body base" "support base") near5 ("via hole" "through hole" "via aperture opening" groove cavity opening aperture via bore bored)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:40
S76	60453	S74 and ("dielectric" "inter- layer dielectric" "insulat\$3" "isolation" passivation) near5 layer	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:42
S77	24209	S76 and (wire wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:42
S78	3461	S77 and resist near3 layer	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:43
S79	346	S77 and "solder resist" near3 layer	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:44
S80	2477	S78 and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:45

S81	129	S80 and (chip die) near4 (optical optic light "optical element")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:47
S82	33	S81 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:48
S83	22	("20010021490"   "4495220"   "4497684"   "4536249"   "4877718"   "4912022"   "5098815"   "5242770"   "5256505"   "5328807"   "5447810"   "5635010"   "5657235"   "5663893"   "5667940"   "5707765"   "5723233"   "5776662"   "5786270"   "6258489").PN. OR ("6548224").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/02 10:50
S84	1648	S80 and (optical optic light "optical element")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:58
S85	485	S84 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/04/02 10:58
S86	116	("3163588"   "4127699"   "4135988"   "4210704"   "4354895"   "4383363"   "4590539"   "4618567"   "4731503"   "4736521"   "4747968"   "4791248"   "4822523"   "4880570"   "4882245"   "4882839"   "4893404"   "4901205"   "4904414"   "4940651"   "4964948"   "4967314"   "4991060"   "4999136"   "5026624"   "5028743"   "5057372"   "5065227"   "5070002"   "5082595"   "5117069"   "5200026"   "5210941"   "5220724"   "5243142"   "5262247"   "5266446"   "5271150"   "5287619"   "5300402"   "5304252"   "5319159"   "5319523"   "5321210"   "5346750"   "5348574"   "5366027"   "5366794"   "5373629"   "5419038"   "5427895"   "5439779"   "5450290"   "5463190"   "5473120"   "5487218"   "5494764"   "5541567"   "5566840"   "5716663"   "5744758"   "5758413"   "5780143"   "5906042"	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/02 11:29



		"5956843"   "5977490"   "6033764").PN. OR ("6178093").URPN.				
S87	2	"20060012967"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 08:50
S88	2	S87 and solder adj resist	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 08:50
S89	1	S87 and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 08:53
S91	4307	(257/621,774).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2010/01/15 09:07
S92	7742	(438/629,630,637- 640,668,672,675).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2010/01/15 09:08
S93	1465	(257/E21.597).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2010/01/15 09:08
S94	348	S91 and ("light emitting" "optical device" "optical element" "photosensitive device" "photodiode" "optoelectronic device" "optoelectronic element" "light sensitive device" "light sensitive element" "photo-electric" "photoelectric")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:15
S95	87	S94 and ("thermosetting resin" "thermoplastic resin" "photosensitive resin" "epoxy resin" "U cured- typeepoxyresin" "polyolefinresin" "acrylic resin" PMMA "polymethyl methacrylate" "PMMA deuteride" "PMMA deuteride fluoride" "polyimide resin" "polyimide fluoride" "silicone resin" "silicone resin deuteride")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:20

S96	9	S95 and ("thermosetting resin" "thermoplastic resin" "photosensitive resin" "epoxy resin" "U cured-typeepoxyresin" "polyolefinresin" "acrylic resin" PMMA "polymethyl methacrylate" "PMMA deuteride" "PMMA deuteride fluoride" "polyimide resin" "polyimide fluoride" "silicone resin" "silicone resin deuteride") near5 ("viahole" "through hole" via hole cavity opening groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:22
S97	3	S96 and @ad<"20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:22
S103	3	S97 and ("polyphenylene ether resin" "polyolefin resin" "fluororesin" "thermoplastic elastomer" "epoxy resin" "polyimide resin" "thermosetting resin" "meth acrylate" "bisphenol" "multivalent acrylic monomer" "glycol ether type solvent")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:30
S104	87	S95 and ("thermosetting resin" "thermoplastic resin" "photosensitive resin" "epoxy resin" "U cured-typeepoxyresin" "polyolefinresin" "acrylic resin" PMMA "polymethyl methacrylate" "PMMA deuteride" "PMMA deuteride fluoride" "polyimide resin" "polyimide fluoride" "silicone resin" "silicone resin deuteride")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:31
S105	75	S104 and ("polyphenylene ether resin" "polyolefin resin" "fluororesin" "thermoplastic elastomer" "epoxy resin" "polyimide resin" "thermosetting resin" "meth acrylate" "bisphenol" "multivalent acrylic monomer" "glycol ether type solvent")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:31

S106	29	S105 and @ad< "20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:32
S107	283	S92 and ("polyphenylene ether resin" "polyolefin resin" "fluororesin" "thermoplastic elastomer" "epoxy resin" "polyimide resin" "thermosetting resin" "meth acrylate" "bisphenol" "multivalent acrylic monomer" "glycol ether type solvent")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:46
S108	268	S107 and ("thermosetting resin" "thermoplastic resin" "photosensitive resin" "epoxy resin" "U cured- typeepoxyresin" "polyolefinresin" "acrylic resin" PMMA "polymethyl methacrylate" "PMMA deuteride" "PMMA deuteride fluoride" "polyimide resin" "polyimide fluoride" "silicone resin" "silicone resin deuteride")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:47
S109	75	S108 and @ad< "20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 09:47
S110	47063	("via hole" "through hole" "via aperture opening" groove cavity opening aperture via bore bored) near5 ("substrate mountig plate" "mounting substrate"pcb "printed circuit board" pwb "printed wiring board" "body base" "support base")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:23
S111	7961	S110 and (LED "light emitting" "optical device" "optical element" "photosensitive device" "photodiode" "optoelectronic device" "optoelectronic element" "light sensitive device" "light sensitive element" "photo-electric" "photoelectric" "light receiving" "photosensitive element" )	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:24

S112	2225	S111 and ("via hole" "through hole" "via aperture opening" groove cavity opening aperture via bore bored) near5 (LED "light emitting" "optical device" "optical element" "photosensitive device" "photodiode" "optoelectronic device" "optoelectronic element" "light sensitive device" "light sensitive element" "photo-electric" "photoelectric" "light receiving" "photosensitive element" )	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:25
S113	284	S112 and ("solder resist" "polyphenylene ether resin" "polyolefin resin" "fluororesin" "thermoplastic elastomer" "epoxy resin" "polyimide resin" "thermosetting resin" "meth acrylate" "bisphenol" "multivalent acrylic monomer" "glycol ether type solvent")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:26
S114	82	S113 and @ad< "20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:27
S115	32	("5394490"   "5521992"   "5600741"   "5696862"   "5761350"   "6389202"). PN. OR ("6512861").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 10:30
S116	19	("20020051599"   "20020097962"   "20040042705"   "20050094922"   "20050180681"   "4732446"   "4897711"   "6236786"   "6330377"   "6477286"   "6483960"   "6512861"   "6529650"   "6754407"   "6810160"). PN. OR ("7263248").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 10:33

S117	28	("20020153829"   "3504214"   "3634714"   "4415403"   "4702566"   "5150005"   "5243142"   "5319159"   "5432015"   "5436744"   "5463191"   "5559399"   "5597518"   "5739634"   "5744285"   "5814935"   "5834327"   "6061105"   "6069443"   "6339197"   "6392356"   "6411349"   "6452117"   "6476783"   "6479763"   "6570639"   "6577057").PN. OR ("7417867").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 10:48
S118	23	S112 and ("solder resist")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:53
S119	3	S118 and @ad< "20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:53
S120	5556	("solder resist") near5 layer	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:54
S121	3971	S120 and ("via hole" "through hole" "via aperture opening" groove cavity opening aperture via bore bored)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:55
S122	446	S121 and (LED "light emitting" "optical device" "optical element" "photosensitive device" "photodiode" "optoelectronic device" "optoelectronic element" "light sensitive device" "light sensitive element" "photo-electric" "photoelectric")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:55
S123	76	S122 and @ad< "20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 10:56
S124	21	("3589000"   "3716761"   "4739448"   "5286926"   "5300402"   "5344893"   "5447996"   "5699613"   "6124408").PN. OR ("6384344").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 11:02

S125	13	("20060180341"   "20070085203"   "4736521"   "5375042"   "5459368"   "5509203"   "5699613"   "5916453"   "6339197"   "6384344"   "6428942"   "6526654"   "6847527").PN. OR ("7489521").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 11:03
S126	9	("20060180341"   "20060231290"   "5509203"   "5699613"   "5916453"   "6384344"   "6428942"   "6847527"). PN. OR ("7262975").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 11:08
S127	16	("20050126818"   "20050236177"   "20060231290"   "20070151758"   "20080055872"   "5590461"   "5713127"   "5758413"   "5875102"   "6078013"   "6487088"   "6591491"   "7091424"   "7102085"   "7262975"   "7339118").PN. OR ("7402760").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 11:08
S128	12	("6272020"   "6326561"   "6329610"   "6370013"   "6373000"   "6392301"   "6426470"   "6480395"   "6495770"   "6506982"). PN. OR ("7102085").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 11:17
S129	1102	("optical path" near5 "optical signal").clm.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 11:33
S130	14	S129 and ibiden	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/15 11:34
S131	6	S130 and ("solder resist"). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/15 11:36
S132	2	("6555876").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2010/01/16 03:53
S133	1	S132 and "source electrode"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/16 03:54
S134	2	"20060012967"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/20 10:45
S135	3	"20040047539"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/20 11:06

S136	11	("20040047539"   "5239189"   "6330377"   "6334014").PN. OR ("7070207").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 11:11
S137	15	("20010023970"   "20030142409"   "20050185880"   "20060012967"   "20060263003"   "20070223935"   "20070297729"   "5105237"   "6330377"   "6334014"   "6623178"   "6661939"   "6788874"   "7070207"   "7149376").PN. OR ("7526152").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 11:12
S138	27	("20020176671"   "20040022496"   "20040042705"   "3777154"   "4732446"   "4966430"   "5600741"   "5764832"   "5786925"   "6233376"   "6257771"   "6330377"   "6427034"   "6439895"   "6457875"   "6512861"   "6869229"   "6912341"   "6944377").PN. OR ("7149376").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 11:13
S139	11	("20040047539"   "5239189"   "6330377"   "6334014").PN. OR ("7070207").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 11:15
S140	25	("4656352"   "4826272"   "4830450"   "4989934"   "5345529"   "5416872"   "5675684"   "5763900"   "6100595"   "6214643"   "6269209"   "6301401").PN. OR ("6623178").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 11:18
S141	29	"5297234"	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 12:43
S142	29	"5297234"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2010/01/20 12:44
S143	1106	("optical path" near5 "optical signal").clm.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 13:05
S144	48	S143 and substrate near5 (insulating insulator)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/20 13:05
S145	21	S144 and @ad< "20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/20 13:05

S146	5564	("solder resist") near5 layer	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/20 13:08
S147	3976	S146 and ("via hole" "through hole" "via aperture opening" groove cavity opening aperture via bore bored)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/20 13:08
S148	1317	S147 and substrate near5 (insulating insulator)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/20 13:08
S149	321	S148 and @ad< "20020301"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/20 13:08
S150	0	S149 and ("optical path")	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 13:09
S151	0	S149 and (optical near5 path)	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 13:09
S152	161	S149 and (optical light optics)	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 13:10
S153	22	S149 and (LED "light emitting" "optical device" "optical element" "photosensitive device" "photodiode" "optoelectronic device" "optoelectronic element" "light sensitive device" "light sensitive element" "photo-electric" "photoelectric")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2010/01/20 13:10
S154	13	("4908933"   "5022960"   "5347712"   "5435480"   "5438478"   "5633069"   "5879787"   "6358630"). PN. OR ("6555208").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 13:13
S155	11	("4816323"   "5243142"   "5346750"   "5484647"   "5744758"   "5766670"   "5972482"   "6010768"   "6376052"   "6440542"   "6753483").PN. OR ("RE40947").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 13:25
S156	29	("4816323"   "5346750"   "5766670"   "6010768"). PN. OR ("6376052").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 13:26
S157	15	("4816323"   "5450290"   "5487218"   "5557844"   "5837155"   "5879568"   "6323439"   "6376052"). PN. OR ("6930258").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/20 13:28

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